

40V N+P Channel Mosfet

FEATURES

- N-Channel: 40V
 $R_{DS(ON)}=19m\Omega$ (Typ.) @ $V_{GS}=10V$
 $R_{DS(ON)}=27m\Omega$ (Typ.) @ $V_{GS}=4.5V$
- P-Channel: -40V
 $R_{DS(ON)}=28m\Omega$ (Typ.) @ $V_{GS}=-10V$
 $R_{DS(ON)}=36m\Omega$ (Typ.) @ $V_{GS}=-4.5V$

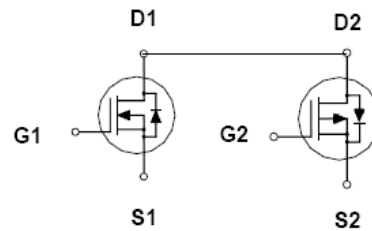
TO-252-4L



APPLICATIONS

- DC FAN
- Networking DC-DC Power System
- Motor Control

N+P CHANNEL MOSFET



Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise specified)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		V_{DS}	40	-40	V
Gate-Source Voltage		V_{GS}	± 20	± 20	V
Continuous Drain Current	$T_C=25^\circ C$	I_D	23	-20	A
	$T_C=100^\circ C$		16.1	-14.0	
Pulsed Drain Current		I_{DM}	46	-40	A
Single Pulse Avalanche Energy		EAS	8.45	18.05	mJ
Avalanche Current		I_{AS}	13.0	-19.0	A
Power Dissipation	$T_C=25^\circ C$	P_D	20.8		W
	$T_C=100^\circ C$		8.3		
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150		$^\circ C$

THERMAL RESISTANCE RATINGS

Thermal Resistance	Symbol	Typ.	Maximum	Unit
Maximum Junction-to-Ambient	$R_{\theta JA}$	-	60	$^{\circ}C/W$
Maximum Junction-to-Case	$R_{\theta JC}$	-	6	$^{\circ}C/W$

N-Channel Electrical Characteristics ($T_C=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=32V, V_{GS}=0V,$ $T_J=25^{\circ}C$	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.2	V
$R_{DS(on)}$ <small>note2</small>	Static Drain-Source on-Resistance	$V_{GS}=10V, I_D=6A$	-	19	24	m Ω
		$V_{GS}=4.5V, I_D=5A$	-	27	37	m Ω
g_{FS}	Forward Transconductance	$V_{DS}=5V, I_D=6A$	-	15	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=20V, V_{GS}=0V,$ $f=1.0MHz$	-	255	310	pF
C_{oss}	Output Capacitance		-	45	60	pF
C_{rSS}	Reverse Transfer Capacitance		-	35	50	pF
Q_g	Total Gate Charge	$V_{DS}=20V, I_D=6A,$ $V_{GS}=10V$	-	5.2	-	nC
Q_{gs}	Gate-Source Charge		-	1.0	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	1.4	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DS}=20V,$ $R_L=2.5\Omega, R_G=3\Omega$	-	4.5	-	ns
t_r	Turn-on Rise Time		-	2.5	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	14.5	-	ns
t_f	Turn-off Fall Time		-	3.5	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	23	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	46	-	A

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

 2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

 3. EAS condition: $T_J=25^{\circ}C, V_{GS}=10V, R_G=25\Omega, L=0.1mH$

P-Channel Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D = -250\mu A$	-40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -32V, V_{GS} = 0V,$	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.6	-2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note2	$V_{GS} = -10V, I_D = -6A$	-	28	36	m Ω
		$V_{GS} = -4.5V, I_D = -5A$	-	36	50	
g_{FS}	Forward Transconductance	$V_{DS} = -5V, I_D = -6A$	-	18	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -20V, V_{GS} = 0V,$ $f = 1.0MHz$	-	760	-	pF
C_{oss}	Output Capacitance		-	140	-	pF
C_{rss}	Reverse Transfer Capacitance		-	95	-	pF
Q_g	Total Gate Charge	$V_{DS} = -20V, I_D = -6A,$ $V_{GS} = -10V$	-	13.6	-	nC
Q_{gs}	Gate-Source Charge		-	2.5	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	3.2	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS} = -20V, R_L = 2.3\Omega,$ $R_{GEN} = 3\Omega, V_{GS} = -10V,$	-	11	-	ns
t_r	Turn-on Rise Time		-	35	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	30	-	ns
t_f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-20	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-40	A

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

3. EAS condition: $T_J = 25^\circ\text{C}$, $V_{GS} = -10V$, $R_G = 25\Omega$, $L = 0.1mH$

N-Channel Typical Performance Characteristics

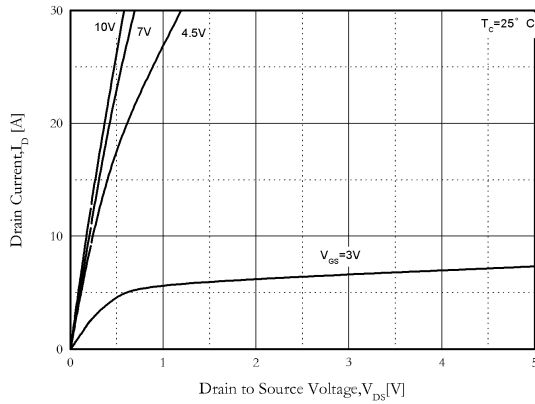


Figure1. Output Characteristics

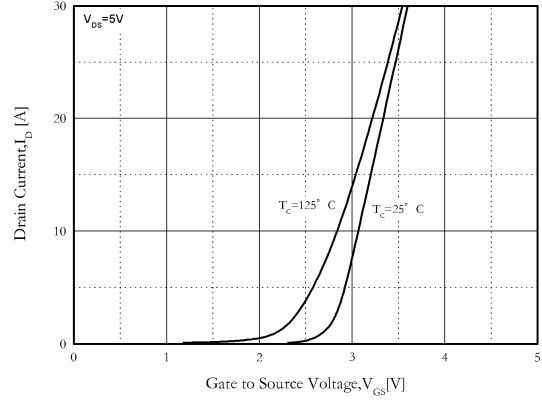


Figure2. Transfer Characteristics

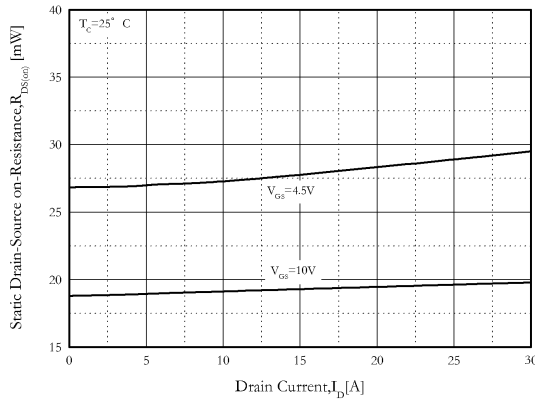


Figure3. $R_{ds(on)}$ -Drain Current

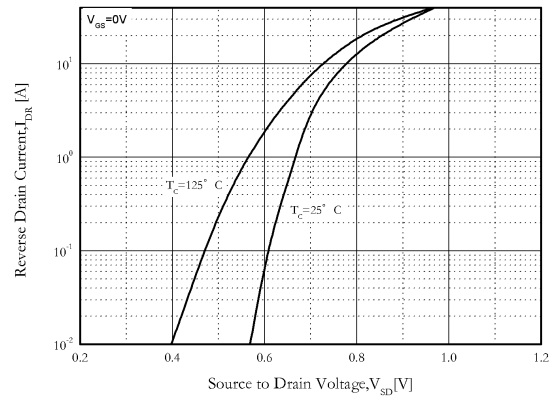


Figure4. Typical Source-Drain Diode Forward Voltage

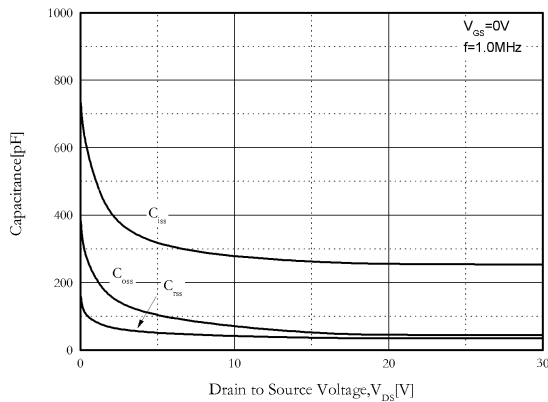


Figure5. Capacitance Characteristics

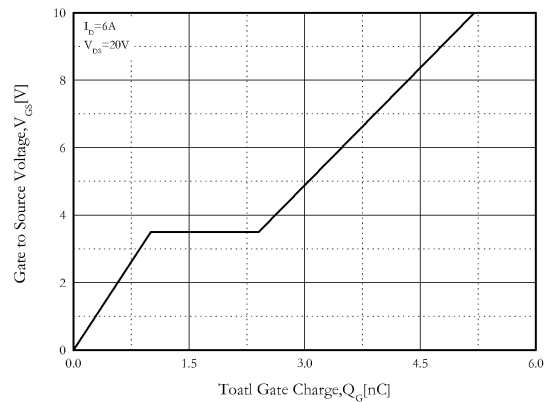


Figure6. Gate Charge

N-Channel Typical Performance Characteristics

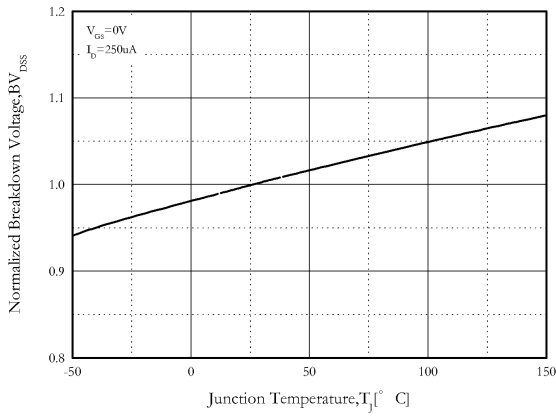


Figure7. Normalized Breakdown Voltage vs. Temperature

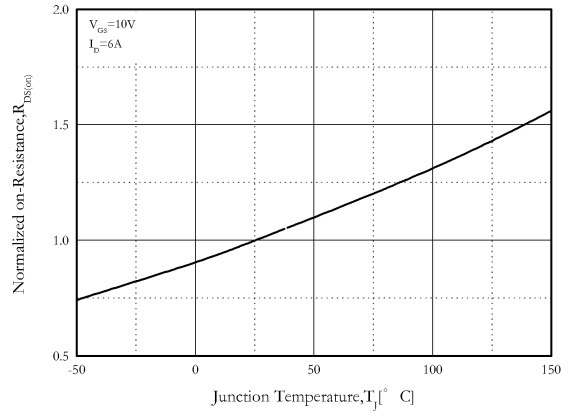


Figure8. Normalized on Resistance vs. Temperature

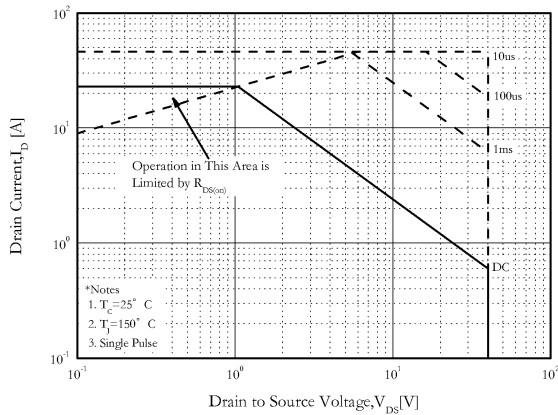


Figure9. Safe Operation Area

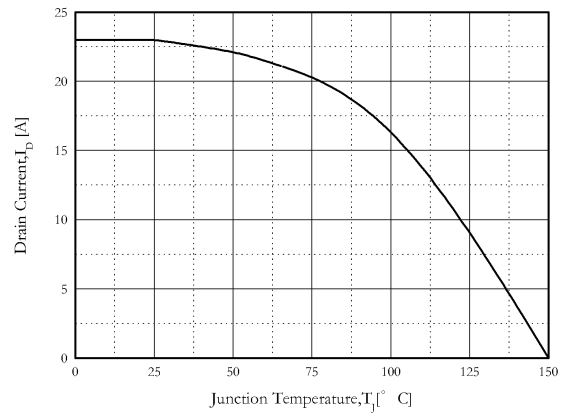


Figure10. Drain Current vs. Junction Temperature

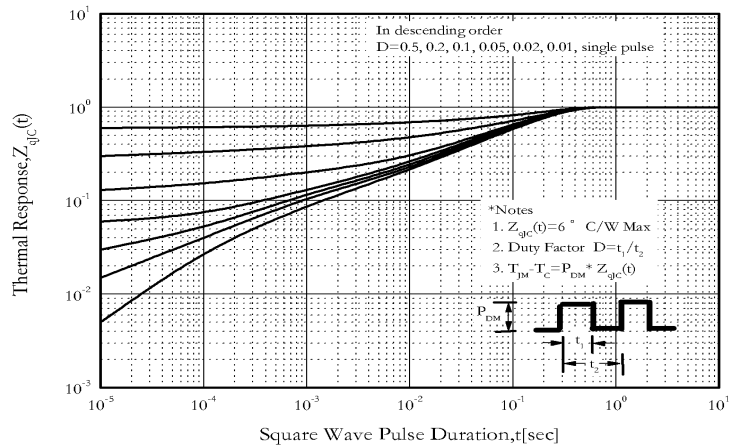


Figure11. Transient Thermal Response Curve

P-Channel Typical Performance Characteristics

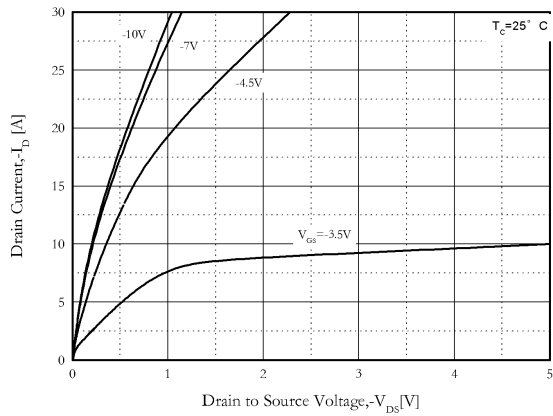


Figure1. Output Characteristics

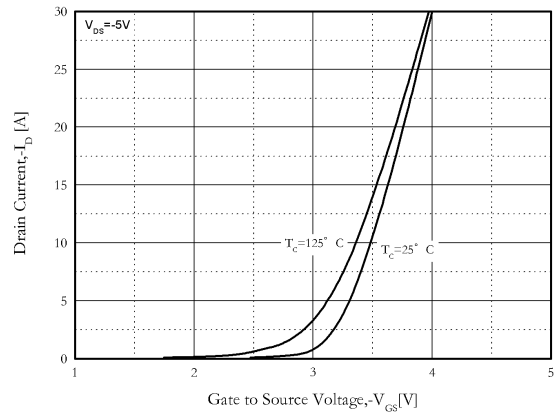


Figure2. Transfer Characteristics

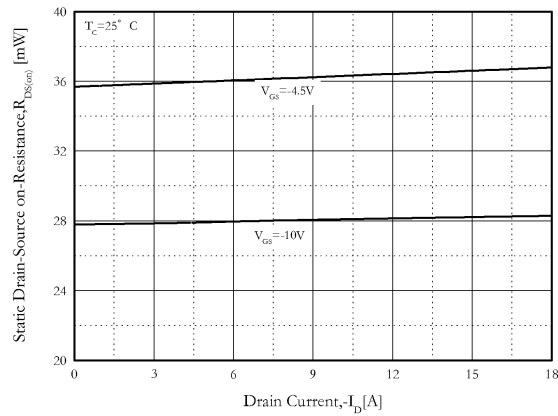


Figure3. Rdson-Drain Current

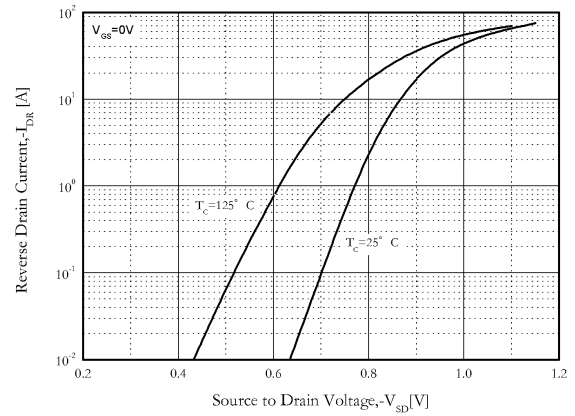


Figure4. Typical Source-Drain Diode Forward Voltage

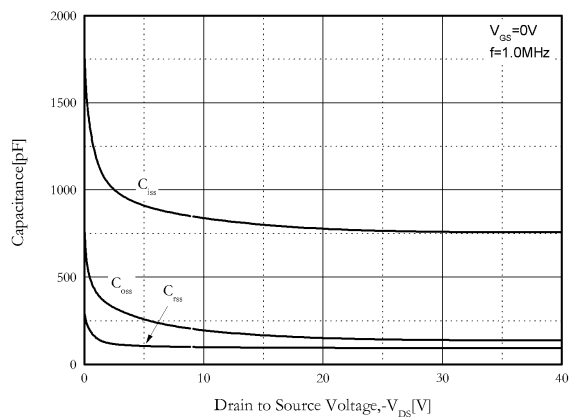


Figure5. Capacitance Characteristics

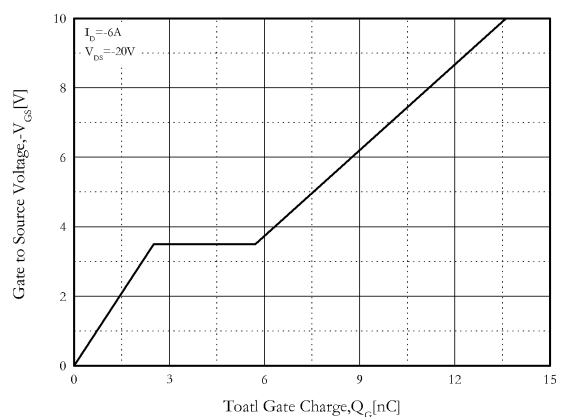


Figure6. Gate Charge

P-Channel Typical Performance Characteristics

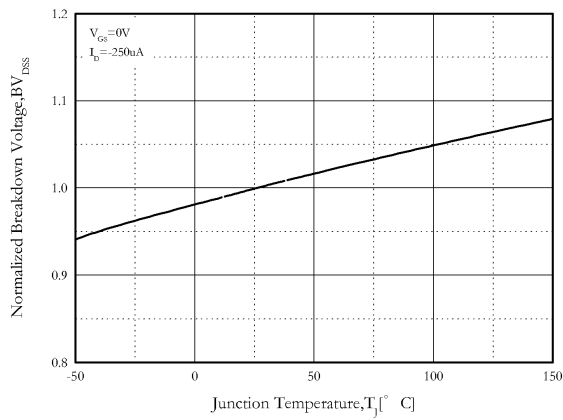


Figure7. Normalized Breakdown Voltage vs. Temperature

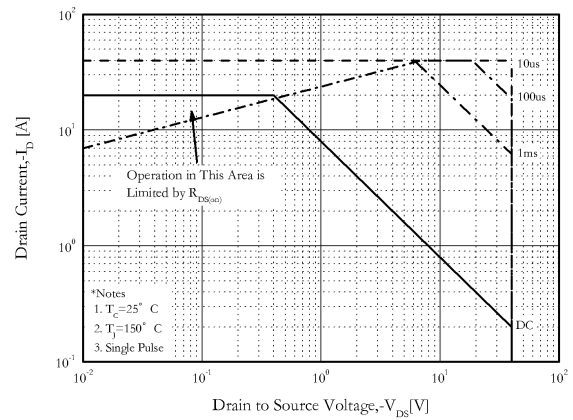


Figure8. Normalized on Resistance vs. Temperature

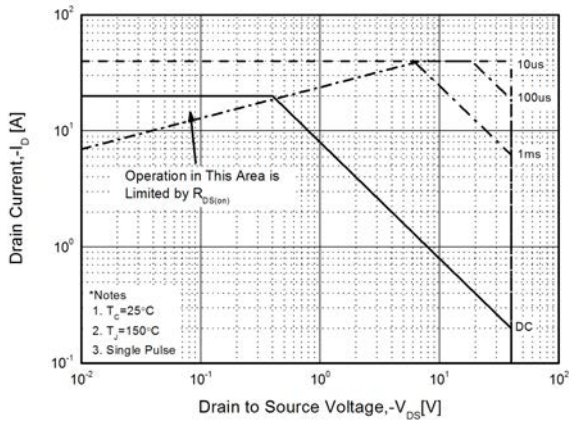


Figure9. Safe Operation Area

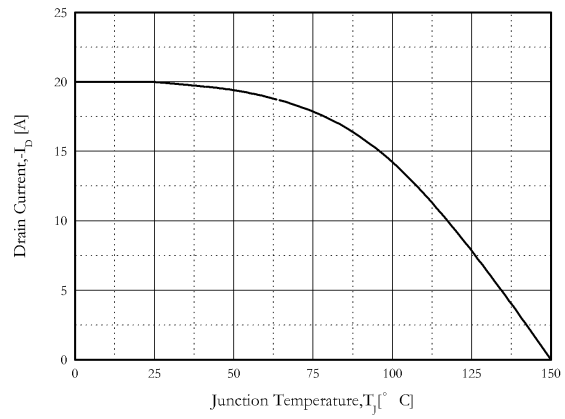


Figure10. Maximum Drain Current vs. Junction Temperature

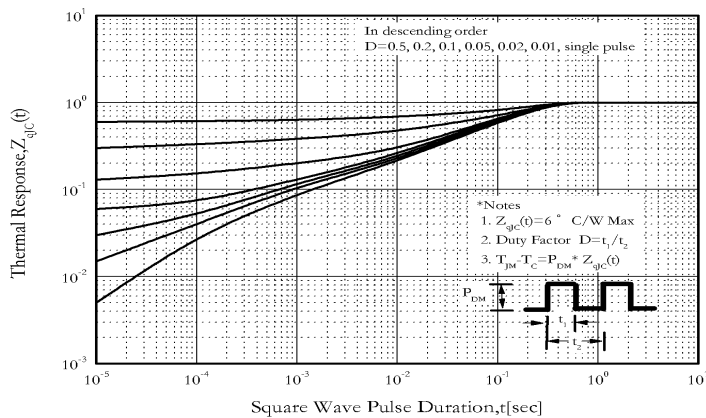
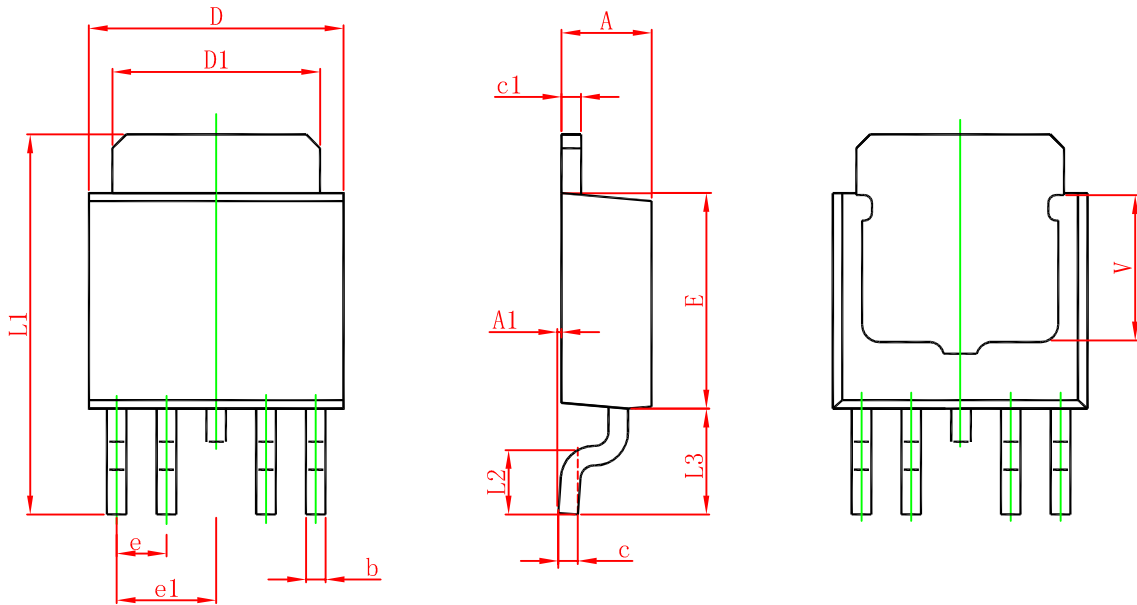


Figure11. Transient Thermal Response Curve

TO-252-4L PACKAGE OUTLINE DRAWING



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.400	0.600	0.016	0.024
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	1.270 TYP		0.050 TYP	
e1	2.540 TYP		1.000 TYP	
L1	9.500	9.900	0.374	0.390
L2	1.400	1.780	0.055	0.070
L3	2.550	2.900	0.100	0.114
V	3.45 REF		0.136 REF	